



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Akram et al.

**Serial No.:** 09/241,177

**Filed:** February 1, 1999

**For:** HIGH DENSITY MODULARITY FOR IC'S

**Examiner:** Unknown

**Group Art Unit:** 2811

**Attorney Docket No.:** 3638US (98-0093)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 39 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

December 12, 2000  
Date of Deposit

Signature of registered practitioner or other person having reasonable basis to expect mailing to occur on date of deposit shown pursuant to 37 C.F.R. § 1.8(a)(1)(ii)

Deidra Pfeil  
Typed/printed name of person whose signature is contained above

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Please revise the above-identified application as follows:

**IN THE SPECIFICATION:**

On page 2, line 24, change "leadframe" to --lead frame--;

On page 3, line 9, insert a period at the end of this line;

On page 3, line 13, delete "areal";

On page 3, line 26, change "el al," to --et al.,--; change "are" to --is--; and change "their" to --its--;

On page 4, line 10, before "through-slots" insert --through--;

On page 4, line 11, change "are" to --is--;

RECEIVED  
DEC 21 2000  
TC 2830 MAIL ROOM